

09/890145

JCT Rec'd PCT/PTO 26 JUL 2001

Docket No.: 56937-027

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Takeshi SUZUKI, et al.

Serial No.:

Filed: July 26, 2001

For: WIRING SUBSTRATE AND MANUFACTURING METHOD THEREOF

#5 Pre Amndt A
D Smalls-Logan
NDJ, 14, D1

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

Prior to examination of the above-referenced application, please amend the application as follows:

IN THE CLAIMS:

Please amend claim 25 as follows:

25. The method for manufacturing a wiring substrate as claimed in [either claim 11 or 14] claim 11, characterized in that said metal conductors are either metal foils or wiring patterns.

Please add new claims 26-28 as follows:

--26. The method for manufacturing a wiring substrate as claimed in claim 12, characterized in that said metal conductors are either metal foils or wiring patterns.

A²
27. The method for manufacturing a wiring substrate as claimed in claim 13,
characterized in that said metal conductors are either metal foils or wiring patterns.

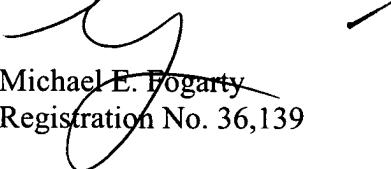
28. The method for manufacturing a wiring substrate as claimed in claim 14,
characterized in that said metal conductors are either metal foils or wiring patterns.--

REMARKS

The above-referenced application is amended to delete the multiple dependency of claim 25 to avoid the multiple dependent claim filing fee.

Respectfully submitted,

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